

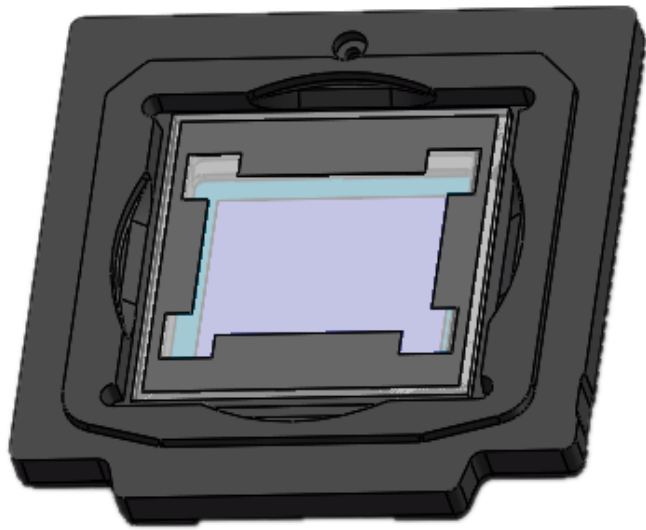
Introduction of COM

- Chip On Module -

(Soldering COB Technology)

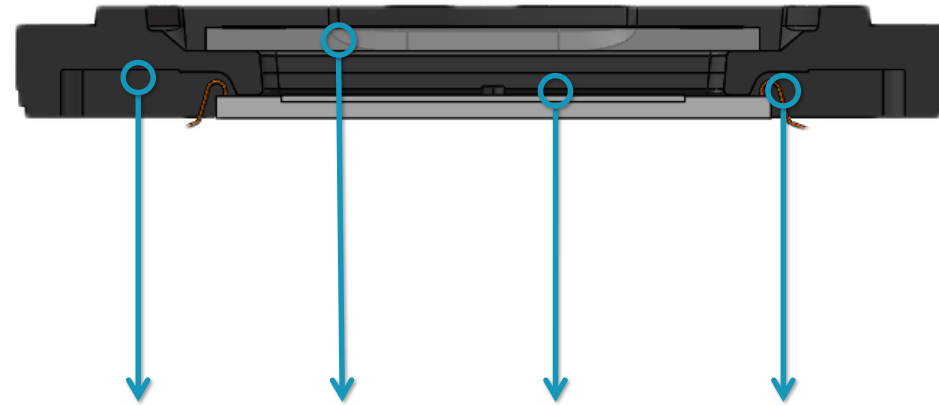
● ——— V4.3 ——— ●

COM Chip



Top View

Side View

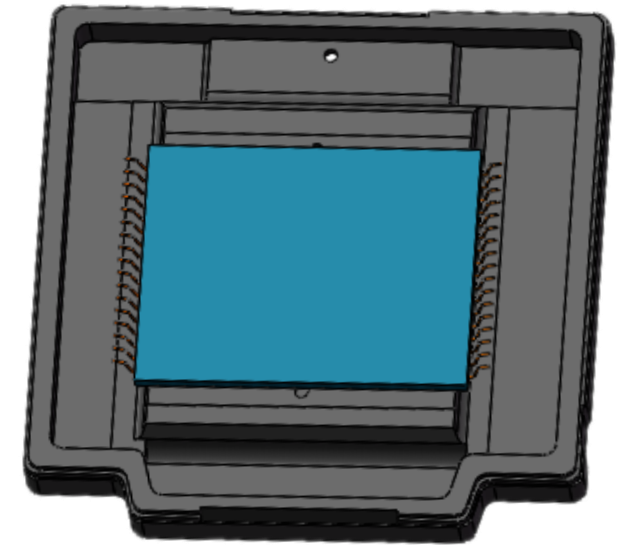


Base

IR Glass

CIS Die

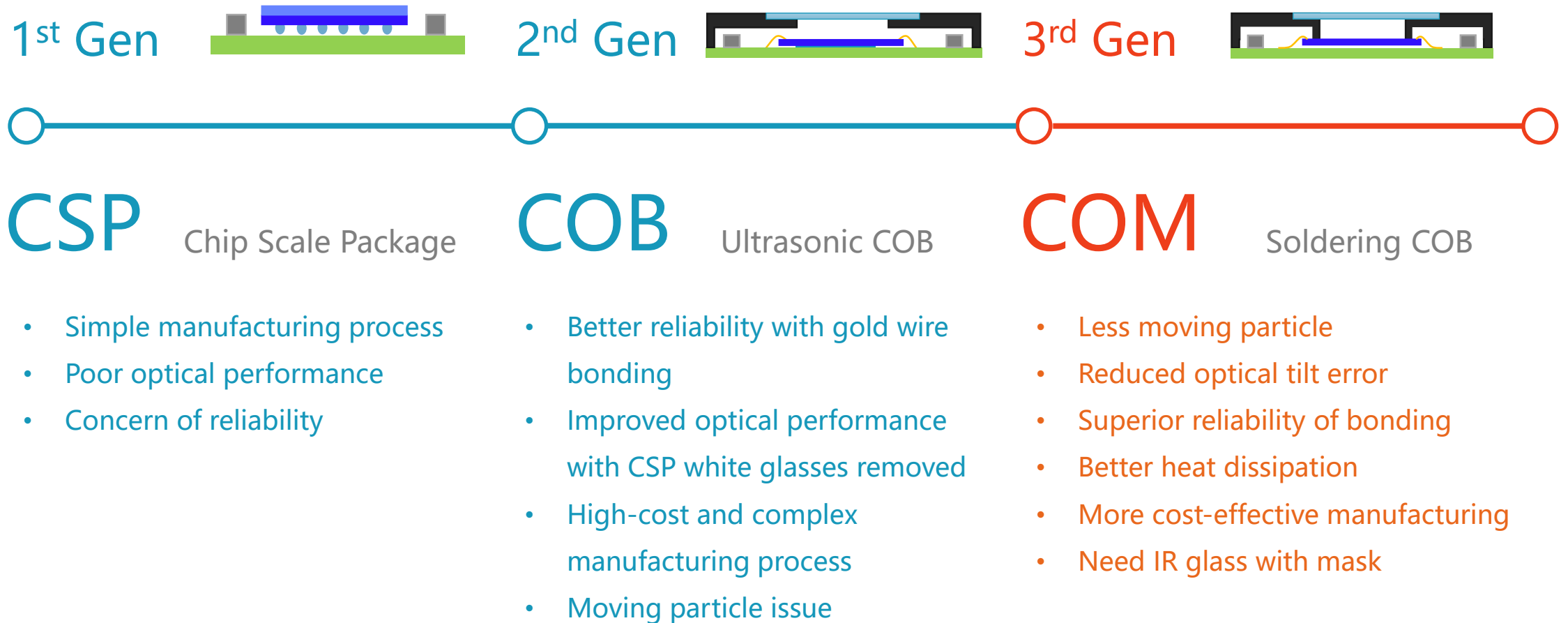
Gold Wire



Bottom View



Soldering COB Technology



COM Roadmap

Series	CIS Model	COM Packaging Size	Status
13M	GC13053	8.5*8.5	Ready
8M	GC08A3	6.5*6.5 / 8.5*8.5	Ready
5M	GC5035	6.5*6.5 / 8.5*8.5	Ready
HD	GC1009	5.6*2.8	Ready

- Product roadmap is subject to change without notice
- Please contact GalaxyCore representative for details



THANKS

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